



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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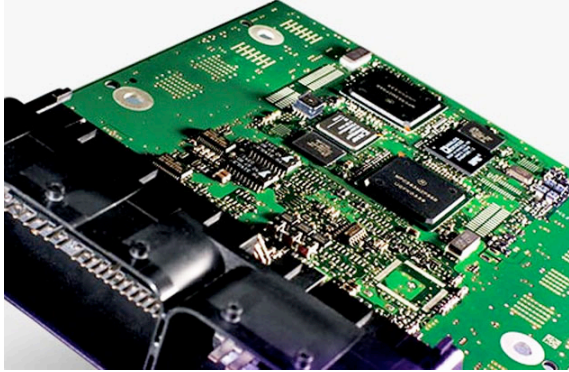
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# TG-NSP-60

## Ultra conformable silicone-free putty type gap filler



### Description

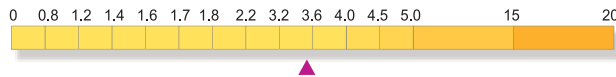
TG-NSP-60 is an ultra conformable silicone-free putty type gap filler. It is designed for when heat transfer is needed between delicate components where the pressure must be minimised and silicone contamination cannot be tolerated. TG-NSP-60 is designed to fill gaps from 0.25 – 8mm with little or no stress generated. The non-silicone formulation will adhere to all surfaces, such as metal housings, ceramic and plastic IC packages and FR4 boards to give a low thermal resistance path for heat transfer.

TG-NSP-60 is available in 30cc syringes, 6 and 12oz cartridges and 5 gallon pails.

### Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 5.9 W/mK  
(W/mK - Z Axis)



Property	TG-NSP-60	Unit	Test Method
Colour	Grey	-	Visual
Thermal Conductivity	5.9	W/mK	ASTM D5470
Weight Loss	<0.5	%	ASTM E595
Working Temperature	-55 to 200	°C	-
Volume Resistivity	$2.15 \times 10^{15}$	Ohm-cm	ASTM D-257
D4-10	0	PPM	GC / MS